

What is claimed is:

1. A film carrier tape for mounting electronic part comprising an insulating film and a wiring pattern which is made of a conductive metal and is provided on
5 the surface of the insulating film, wherein:

an undercoating layer containing nickel as a main constituent is formed on at least a part of the surface of the wiring pattern made of a conductive metal, an intermediate layer containing palladium as a main
10 constituent is formed on the surface of the undercoating layer, a surface layer containing gold as a main constituent is formed on the surface of the intermediate layer, and the average thickness of the intermediate layer containing palladium as a main constituent is not
15 more than 0.04 μm .

2. The film carrier tape for mounting electronic part as claimed in claim 1, wherein the ratio of the average thickness of the intermediate layer containing
20 palladium as a main constituent to the average thickness of the surface layer containing gold as a main constituent (palladium:gold) is in the range of 1:2.5 to 1:1000.

3. The film carrier tape for mounting electronic part as claimed in claim 1, wherein the ratio of the average thickness of the intermediate layer containing palladium as a main constituent to the average thickness of the undercoating layer containing nickel as a main constituent (palladium:nickel) is in the range of 1:2.5 to 1:2500.

4. The film carrier tape for mounting electronic part as claimed in claim 1, wherein the ratio of the average thickness of the surface layer containing gold as a main constituent to the average thickness of the undercoating layer containing nickel as a main constituent (gold:nickel) is in the range of 1:0.05 to 1:50.

5. The film carrier tape for mounting electronic part as claimed in claim 1, wherein the surface of the surface layer containing gold as a main constituent has a gold content of not less than 93% by atom and has a nickel content of not more than 5% by atom.

6. The film carrier tape for mounting electronic part as claimed in claim 1, wherein the surface of the

surface layer containing gold as a main constituent has a copper content of not more than 3% by atom.

7. The film carrier tape for mounting electronic
5 part as claimed in claim 1, wherein the undercoating layer containing nickel as a main constituent, the intermediate layer containing palladium as a main constituent and the surface layer containing gold as a main constituent are formed at the inner terminal of the
10 wiring pattern electrically connected to the electronic part and/or the outer terminal of the film carrier.

8. The film carrier tape for mounting electronic
part as claimed in claim 1, wherein the wiring pattern
15 made of a conductive metal is formed from copper or a copper alloy.